



IEEE NEWS FOR MAY 2012

Jacob Z. Schanker, P.E., Newsletter Chair
Rochester IEEE home page at: <http://rochester.r1.ieee.org>

Rochester Section Meeting – Tuesday, May 1, 2012 at 12 Noon

The May Rochester Section business meeting on Tuesday, May 1, 2012 at 12:00pm, at the Shanghai Restaurant, 2920 West Henrietta Road, just south of the intersection with Brighton-Henrietta Town Line Road.

Any IEEE member is welcome to attend and to participate, or just to observe. Lunch is \$3 for IEEE members. No reservation or RSVP is needed, just show up. Come to celebrate May Day or to enjoy the renowned Shanghai cuisine.

Electromagnetic Compatibility (EMC) and Product Safety Engineering (PSE) Joint Chapter

The EMC/PSE Joint Chapter will meet at RIT on May 9, 2012 for three short topics on EMI Reduction Materials – all in one meeting.

Speakers and Presentations:

- Scott Casper, EMI Gasket Design and Applications
- Peter Torok, Engineered Conductive Thermoplastics in Electronic Applications
- Brian Hantzis, New Technology Development in EMI/RFI Gasket Materials

Date: Wednesday, May 9, 2012

Time: 6:00pm -- Networking & Refreshments
6:30pm – Presentations begin

Location: Room 1355, Orange Hall (Building 13) Rochester Institute of Technology,
One Lomb Memorial Drive, Rochester, NY 14623

RSVP by May 7 (to arrange food & beverages) to james.shipkowski@ieee.org

Cost: Free

Abstracts:

EMI Gasket Design and Applications will begin with initial decision points and progress through design considerations including shielding effectiveness and environmental matters. Material specifications and cost, tolerances, groove designs for extrusions, and die-cut designs for sheets will be discussed. A brief Finite Element Analysis comparison will be reviewed.

Engineered Conductive Thermoplastics in Electronic Applications will treat the advantages of conductive thermoplastics for portable electronics. Comparisons to traditional plastic shielding, and manufacturing and fabrication options will be presented. Material composition and shielding performance will be addressed. Applications, plus an Example Product and tradeoffs will be discussed.

New Technology Development in EMI/RFI Gasket Materials will review Ni/Al, Ecoplate, and Form-In-Place. Ni/Al is a new corrosion resistant silicone and fluorosilicone with a Ni/Al particle that provides the same shielding effectiveness and corrosion resistance as the higher cost military grade materials. Ecoplate is a machine applied conductive coating that has a high bonding strength. It resists flaking and abrasion by bonding with the base material using heat instead of a chemical bonding method. Form-in-Place gaskets may be applied using robotic methods. This effectively bonds the gasket to the housing while eliminating gasket application labor cost.

Speaker Biographies:

Scott Casper is an Applications Engineer with the Chomerics Division of Parker Hannifin Corporation. He has been with Chomerics for 12 years, starting as a process engineer in the Metals unit. As an Ecoplate process engineer he developed a new molding process and during a stint in R&D developed new machinery for new materials and processes. Mr. Casper became an Applications Engineer in 2006.

Peter Torok is the Program Manager for Premier conductive plastics and electronics programs at the Chomerics Division of Parker Hannifin Corporation. With Chomerics 7 years, he started as a project engineer in the Webster Plastics unit. In his present position since 2006, Mr. Torok has been instrumental in improving manufacturing efficiency and expanding Premier applications to include military, consumer, and automotive areas.

Brian Hantzis is a Territory Sales Engineer in the Chomerics Division of Parker Hannifin Corporation. He has been with Chomerics for 28 years, serving as Quality Control Manager, Quality Assurance Manager, Optical Products Engineer and Sales Engineer. Mr. Hantzis was a member of the team that developed the Premier material. He has been designing EMI/RFI Shielding and Thermal Management materials into Military, Telecom, Medical and Industrial applications since 1997.

GRSS Meeting Identified Glacier's Worst Enemy

In a very interesting and engaging talk, NASA Emeritus Scientist and IEEE Geoscience and Remote Sensing Society (GRSS) Distinguished Speaker Dr. Robert Bindschadler (in white t-shirt) explains how Antarctic ice sheets are losing mass through an audience participation skit. Dr. Bindschadler spoke recently to the Western New York Chapter of GRSS. Approximately 80 attendees heard Dr. Bindschadler, at the University of Buffalo's Center for the Arts, explain how ice sheets hate "water" and heard tales of his numerous field campaigns to Antarctica.



May's free e-book for members is on negotiation and innovation

IEEE-USA's free e-book to members in May focuses on Negotiation & Innovation. The downloadable e-book, "Innovation Conversations, Book 1: The Innovation Process" will be available free. The nonmember price is \$5.99.

In "Innovation Conversations, Book 1: The Innovation Process," renowned innovation authority, William C. Miller, guides readers on how to understand the innovation process. He also demonstrates how technology workers can apply it to the challenges and opportunities they find in their day-to-day work. IEEE members can download this free

e-book in May, or any of the other approximately three dozen free e-books, at:
<http://www.ieeeusa.org/communications/ebooks/>.

If you are not yet a member, you can learn about the many benefits of IEEE membership by visiting: http://www.ieee.org/membership_services/membership/join/.